

**ABSTRACT**

A package for packaging a semiconductor die is provided that increases the reliability of packaged semiconductor circuits in particular in high frequency applications where  
5 both analog and digital signals are used. The package comprises a first die attach paddle which is connectable to a first part of a bottom surface of the semiconductor die, and a second die attach paddle which is connectable to a second part of the bottom surface of the semiconductor die. The first and second die attach paddles are each made of an electrically conductive material, and are electrically separated  
10 from each other. Further, a corresponding semiconductor device and a method of fabricating a package and packaging a semiconductor die are provided. When packaging dies having analog and digital circuits, separate grounds not only on the chip but also in the package can be achieved so that cross talking problems can be effectively reduced.